CD4094B Types

CMOS
8-Stage Shift-and-Store
Bus Register

High-Voltage Types (20-Volt Rating)
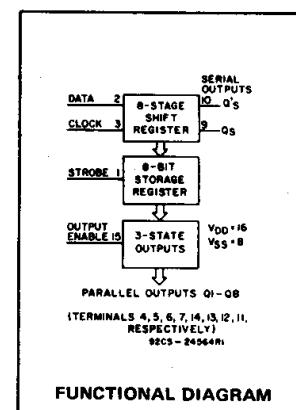
■ CD4094B is an 8-stage serial shift register having a storage latch associated with each stage for strobing data from the serial input to parallel buffered 3-state outputs. The parallel outputs may be connected directly to common bus lines. Data is shifted on positive clock transitions. The data in each shift register stage is transferred to the storage register when the STROBE input is high. Data in the storage register appears at the outputs whenever the OUTPUT-ENABLE signal is high.

Two serial outputs are available for cascading a number of CD4094B devices. Data is available at the Q_S serial output terminal on positive clock edges to allow for high-speed operation in cascaded systems in which the clock rise time is fast. The same serial information, available at the Q'_S terminal on the next negative clock edge, provides a means for cascading CD4094B devices when the clock rise time is slow.

The CD4094B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

Features:

■ 3-state parallel outputs for connection to common bus
■ Separate serial outputs synchronous to both positive and negative clock edges for cascading
■ Medium speed operation – 5 MHz at 10 V (typ.)
■ Standardized, symmetrical output characteristics
■ 100% tested for quiescent current at 20 V
■ Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
■ Noise margin (full package temperature range):
  1 V at V_{DD} = 5 V   2 V at V_{DD} = 10 V
              2.5 V at V_{DD} = 15 V
■ 5-V, 10-V, and 15-V parametric ratings
■ Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications:

■ Serial-to-parallel data conversion
■ Remote control holding register
■ Dual-rank shift, hold, and bus applications

FUNCTIONAL DIAGRAM
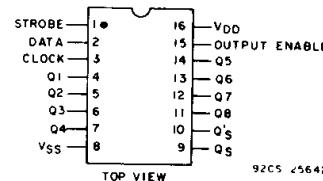
Fig. 1 – Terminal assignment.

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
  Voltages referenced to V_{SS} Terminal) .... –0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS .... –0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT .... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
  For T_A = –55°C to +100°C 500mW
  For T_A = +100°C to +125°C .... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
  FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) .... –55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) .... –65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
  At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max .... +265°C
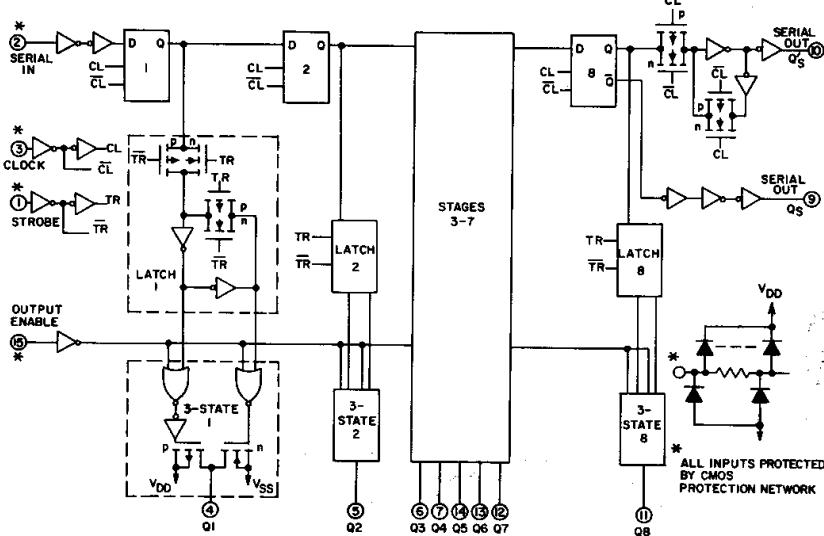
Fig. 2 – CD4094B Logic diagram.
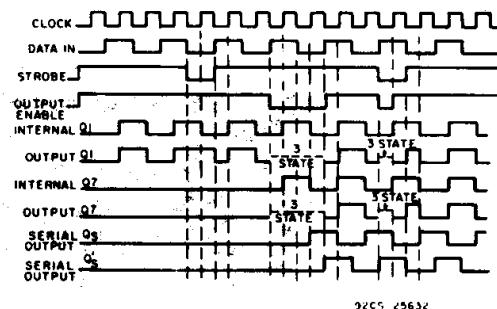
Fig. 3 – Timing diagram.

RECOMMENDED OPERATING CONDITIONS at $T_A = 25°C$, Except as Noted.
For maximum reliability, nominal operating conditions should be selected so that
operation is always within the following ranges:

CHARACTERISTIC	VDD (V)	LIMITS		UNITS
		MIN.	MAX.	
Supply-Voltage Range (For T_A=Full Package-Temperature Range)		3	18	V
Data Setup Time, t_S	5	125	—	ns
	10	55	—	
	15	35	—	
Clock Pulse Width, t_W	5	200	—	ns
	10	100	—	
	15	83	—	
Clock Input Frequency, f_{CL}	5	dc	1.25	MHz
	10		2.5	
	15		3	
Clock Input Rise or Fall time, t_rCL, t_fCL:*	5	—	15	μs
	10		5	
	15		5	
Strobe Pulse Width, t_W	5	200	—	ns
	10	80	—	
	15	70	—	

*If more than one unit is cascaded t_fCL (for Q_S only) should be made less than or equal
to the sum of the fixed propagation delay at 50 pF and the transition time of the output
driving stage for the estimated capacitive load.

TRUTH TABLE

CL▲	Output Enable	Strobe	Data	Parallel Outputs		Serial Outputs	
				Q1	QN	QS*	Q'S
⌐_	0	X	X	OC	OC	Q7	NC
⌐_	0	X	X	OC	OC	NC	Q7
_/	1	0	X	NC	NC	Q7	NC
_/	1	1	0	0	QN-1	Q7	NC
⌐_	1	1	1	1	QN-1	Q7	NC
⌐_	1	1	1	NC	NC	NC	Q7

▲ = Level Change   Logic 1 ≡ High
X = Don't Care   Logic 0 ≡ Low
NC = No Change
OC = Open Circuit

* At the positive clock edge information in the 7th shift register
stage is transferred to the 8th register stage and the Q_S output.
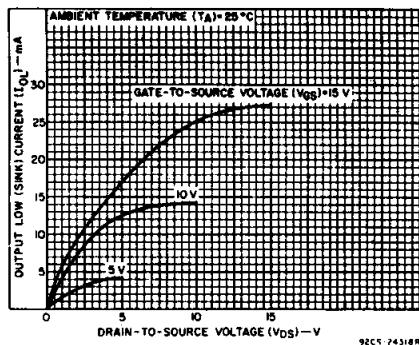
Fig. 4 — Typical output low (sink) current
characteristics.
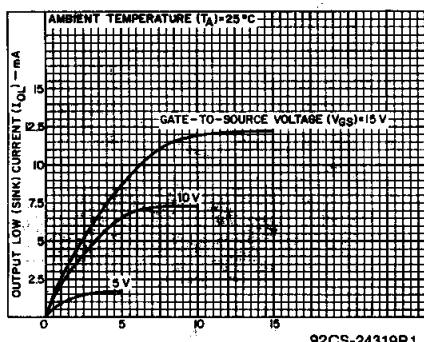
Fig. 5 — Minimum output low (sink) current
characteristics.
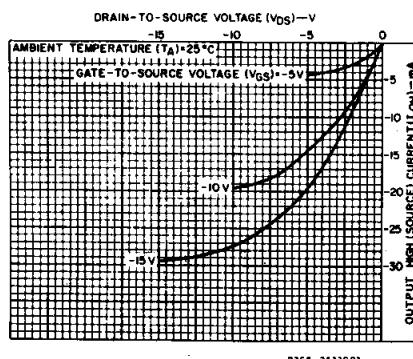
Fig. 6 — Typical output high (source) current
characteristics.
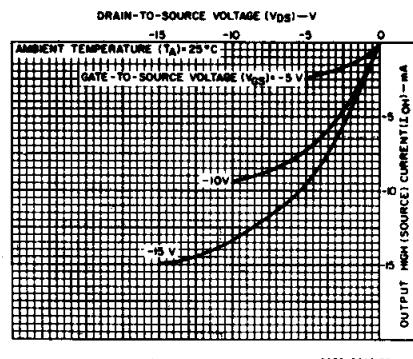
Fig. 7 — Minimum output high (source) current
characteristics.
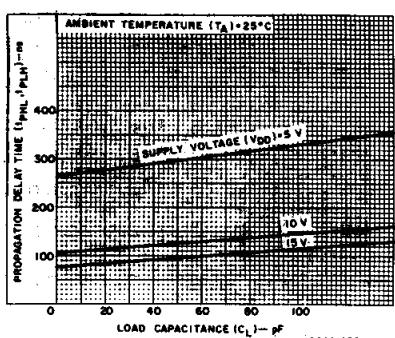
Fig. 8 — Clock-to-serial output Q_S propagation
delay vs C_L.
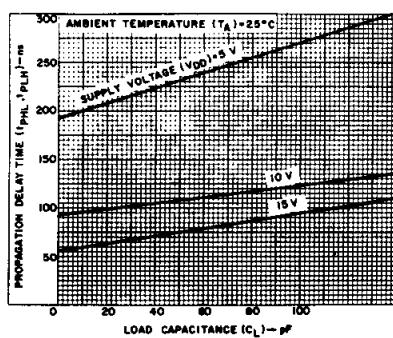
Fig. 9 — Clock-to-serial output Q'_S propagation
delay vs C_L.
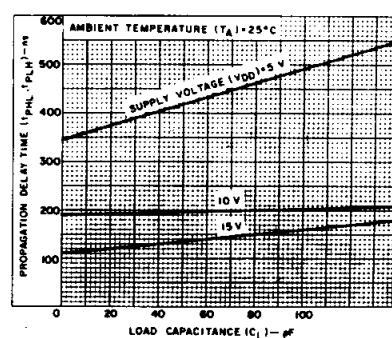
Fig. 10 — Clock-to-parallel output propagation
delay vs C_L.

STATIC ELECTRICAL CHARACTERISTICS

| CHARACTERISTIC	CONDITIONS Vo (V)	VIN (V)	VDD (V)	LIMITS AT INDICATED TEMPERATURES (°C) −55	−40	+85	+125	+25 Min.	Typ.	Max.	UNITS
Quiescent Device Current, IDD Max.	–	0,5	5	5	5	150	150	–	0.04	5	µA
	–	0,10	10	10	10	300	300	–	0.04	10	
	–	0,15	15	20	20	600	600	–	0.04	20	
	–	0,20	20	100	100	3000	3000	–	0.08	100	
Output Low (Sink) Current, IOL Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	–	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	–	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	–	
Output High (Source) Current, IOH Min.	4.6	0,5	5	−0.64	−0.61	−0.42	−0.36	−0.51	−1	–	
	2.5	0,5	5	−2	−1.8	−1.3	−1.15	−1.6	−3.2	–	
	9.5	0,10	10	−1.6	−1.5	−1.1	−0.9	−1.3	−2.6	–	
	13.5	0,15	15	−4.2	−4	−2.8	−2.4	−3.4	−6.8	–	
Output Voltage: Low-Level, VOL Max.	–	0,5	5	0.05				–	0	0.05	V
	–	0,10	10	0.05				–	0	0.05	
	–	0,15	15	0.05				–	0	0.05	
Output Voltage: High-Level, VOH Min.	–	0,5	5	4.95				4.95	5	–	
	–	0,10	10	9.95				9.95	10	–	
	–	0,15	15	14.95				14.95	15	–	
Input Low Voltage, VIL Max.	0.5, 4.5	–	5	1.5				–	–	1.5	V
	1, 9	–	10	3				–	–	3	
	1.5,13.5	–	15	4				–	–	4	
Input High Voltage, VIH Min.	0.5, 4.5	–	5	3.5				3.5	–	–	V
	1, 9	–	10	7				7	–	–	
	1.5,13.5	–	15	11				11	–	–	
Input Current IIN Max.	–	0,18	18	±0.1	±0.1	±1	±1	–	±10^{-5}	±0.1	µA
3-State Output Leakage Current IOUT Max.	0,18	0,18	18	±0.4	±0.4	±12	±12		±10^{-4}	±0.4	µA
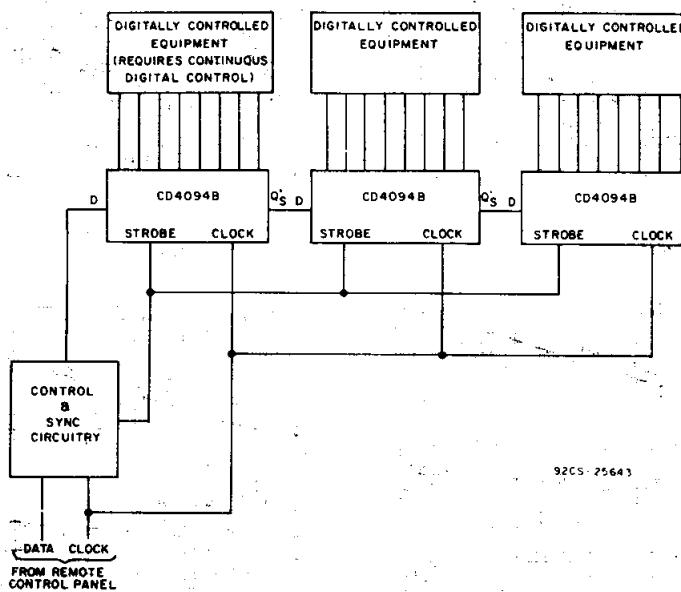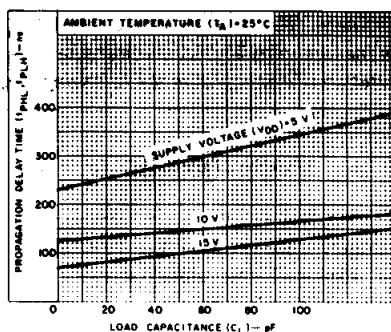
Fig. 11 – Strobe-to-parallel output propagation delay vs C_L.
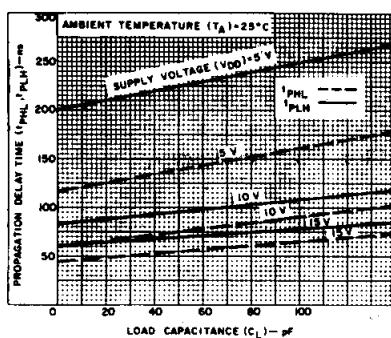
Fig. 12 – Output enable-to-parallel output propagation delay vs C_L.
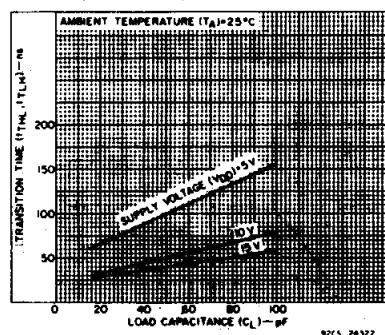
Fig. 13 – Typical transition time vs. load capacitance.
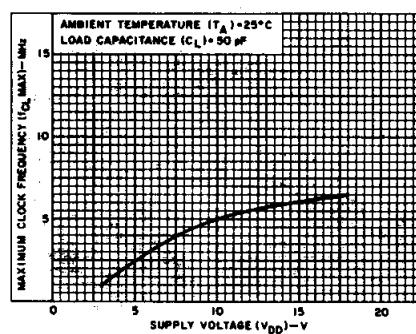
Fig. 15 – Typical maximum-clock-frequency vs. supply voltage.

Fig. 14 – Remote control holding register.

DYNAMIC ELECTRICAL CHARACTERISTICS

At $T_A = 25°C$; Input t_r, $t_f = 20\,ns$, $C_L = 50\,pF$, $R_L = 200\,k\Omega$

CHARACTERISTIC	V_{DD} (V)	LIMITS			UNITS
		MIN.	TYP.	MAX.	
Propagation Delay Time, t_{PHL}, t_{PLH} Clock to Serial Output Q_S	5	—	300	600	
	10	—	125	250	ns
	15	—	95	190	
Clock to Serial Output Q_S'	5	—	230	460	
	10	—	110	220	ns
	15	—	75	150	
Clock to Parallel Output	5	—	420	840	
	10	—	195	390	ns
	15	—	135	270	
Strobe to Parallel Output	5	—	290	580	
	10	—	145	290	ns
	15	—	100	200	
Output Enable to Parallel Output: t_{PHZ}, t_{PZH}	5	—	140	280	
	10	—	60	120	ns
	15	—	45	90	
t_{PLZ}, t_{PZL}	5	—	100	200	
	10	—	50	100	ns
	15	—	40	80	
Minimum Strobe Pulse Width, t_W	5	—	100	200	
	10	—	40	80	ns
	15	—	35	70	
Minimum Clock Pulse Width, t_W	5	—	100	200	
	10	—	50	100	ns
	15	—	40	83	
Minimum Data Setup Time, t_S	5	—	60	125	
	10	—	30	55	ns
	15	—	20	35	
Transition Time; t_{THL}, t_{TLH}	5	—	100	200	
	10	—	50	100	ns
	15	—	40	80	
Maximum Clock Input Rise or Fall Time, $t_r CL$, $t_f CL$	5	15	—	—	
	10	5	—	—	μs
	15	5	—	—	
Maximum Clock Input Frequency, f_{CL}	5	1.25	2.5	—	
	10	2.5	5	—	MHz
	15	3	6	—	
Input Capacitance C_{IN} (Any Input)	—	—	5	7.5	pF

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils $(10^{-3}$ inch).
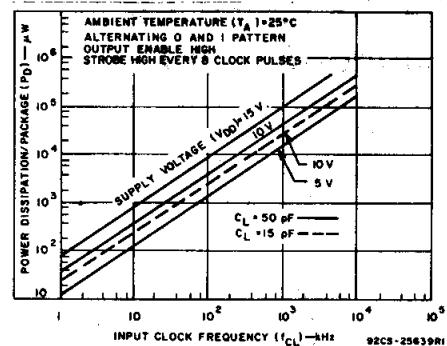

Fig. 16 — Dynamic power dissipation vs input clock frequency.
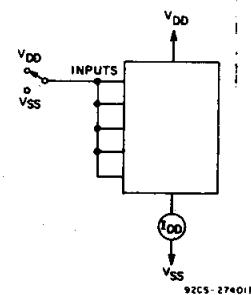
Fig. 17 — Quiescent device current test circuit.
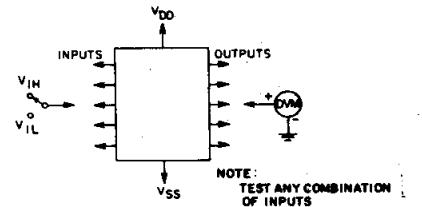


Fig. 18 — Input voltage test circuit.
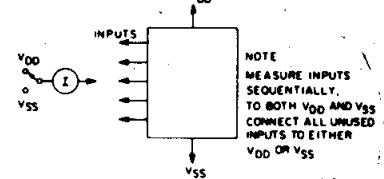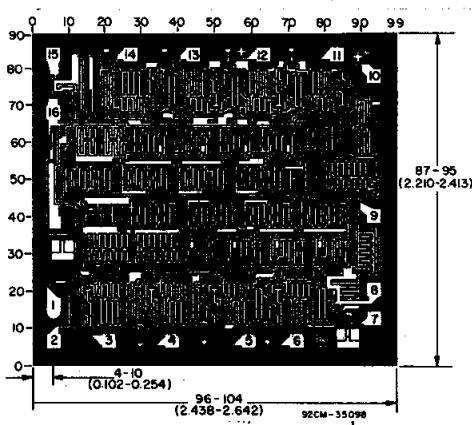
Fig. 19 — Input current test circuit.

Dimensions and Pad Layout for CD4094B Chip.

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable part number (1)	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
7702501EA	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7702501EA CD4094BF3A
CD4094BE	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4094BE
CD4094BE.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4094BE
CD4094BEE4	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4094BE
CD4094BF	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4094BF
CD4094BF.A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4094BF
CD4094BF3A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7702501EA CD4094BF3A
CD4094BF3A.A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	7702501EA CD4094BF3A
CD4094BNSR	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4094B
CD4094BNSR.A	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4094B
CD4094BNSR.B	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4094B
CD4094BPW	Obsolete	Production	TSSOP (PW) | 16	-	-	Call TI	Call TI	-55 to 125	CM094B
CD4094BPWR	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-55 to 125	CM094B
CD4094BPWR.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM094B
CD4094BPWRG4	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM094B

(1) Status: For more details on status, see our product life cycle.

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.
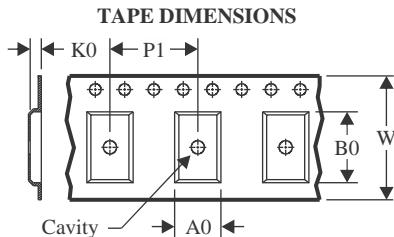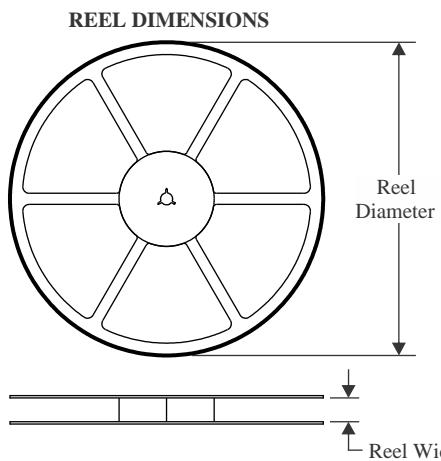
OTHER QUALIFIED VERSIONS OF CD4094B, CD4094B-MIL :

- Catalog : CD4094B

- Military : CD4094B-MIL

NOTE: Qualified Version Definitions:
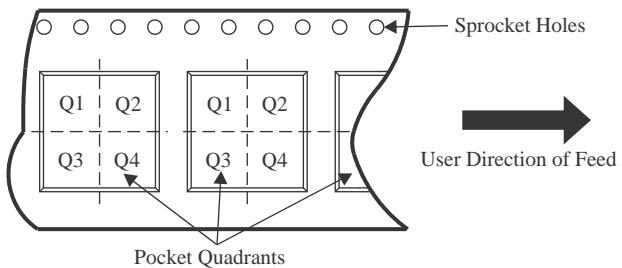
- Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS
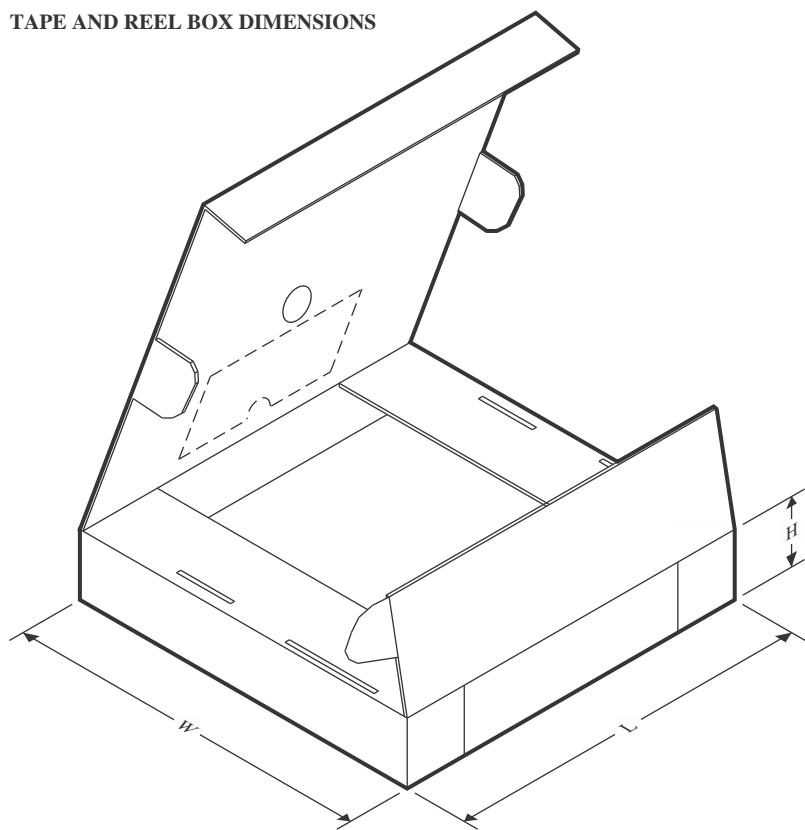
TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE
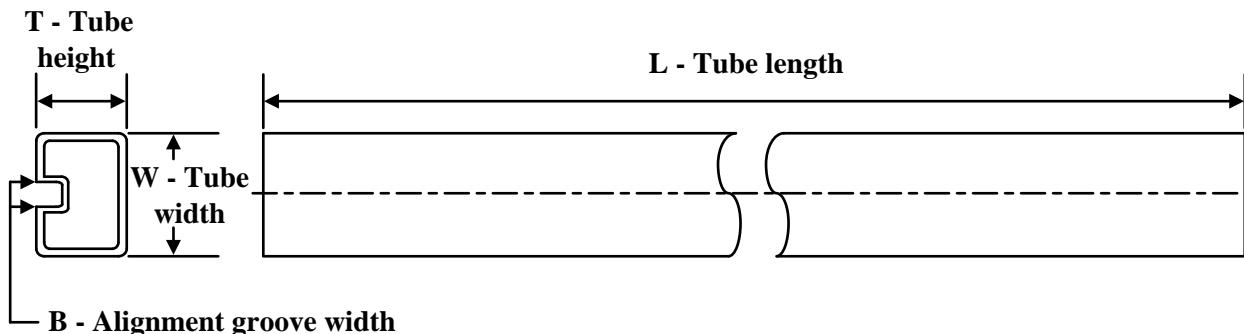
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4094BNSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
CD4094BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD4094BPWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4094BNSR	SOP	NS	16	2000	353.0	353.0	32.0
CD4094BPWR	TSSOP	PW	16	2000	353.0	353.0	32.0
CD4094BPWRG4	TSSOP	PW	16	2000	356.0	356.0	35.0

TUBE
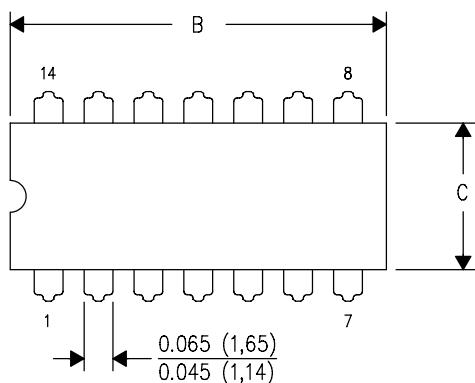
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD4094BE	N	PDIP	16	25	506	13.97	11230	4.32
CD4094BE.A	N	PDIP	16	25	506	13.97	11230	4.32
CD4094BEE4	N	PDIP	16	25	506	13.97	11230	4.32
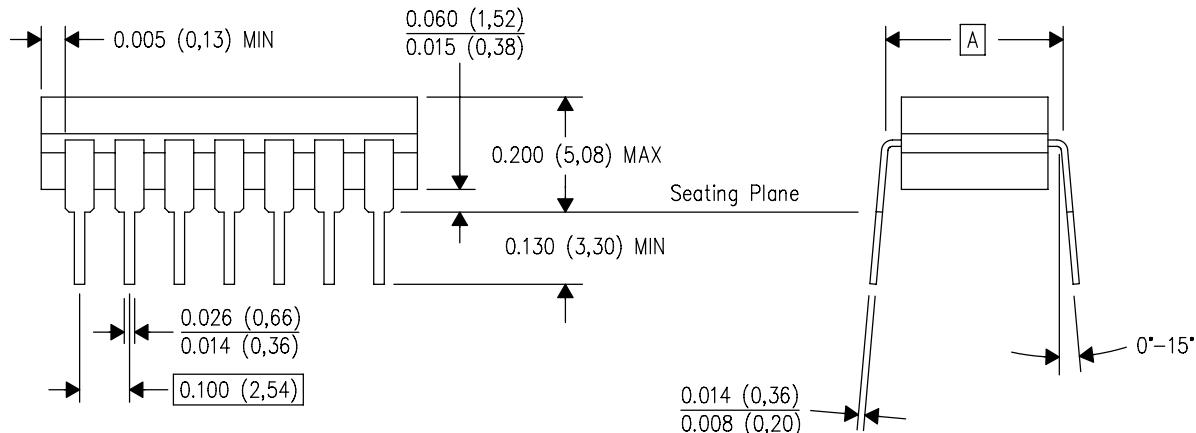
DIM \ PINS ∗∗	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

0.065 (1,65)
0.045 (1,14)

1   7

C

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

A

0°−15°

0.014 (0,36)
0.008 (0,20)
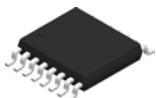
4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. This package is hermetically sealed with a ceramic lid using glass frit.
         D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E. Falls within MIL STD 1835 GDIP1−T14, GDIP1−T16, GDIP1−T18 and GDIP1−T20.
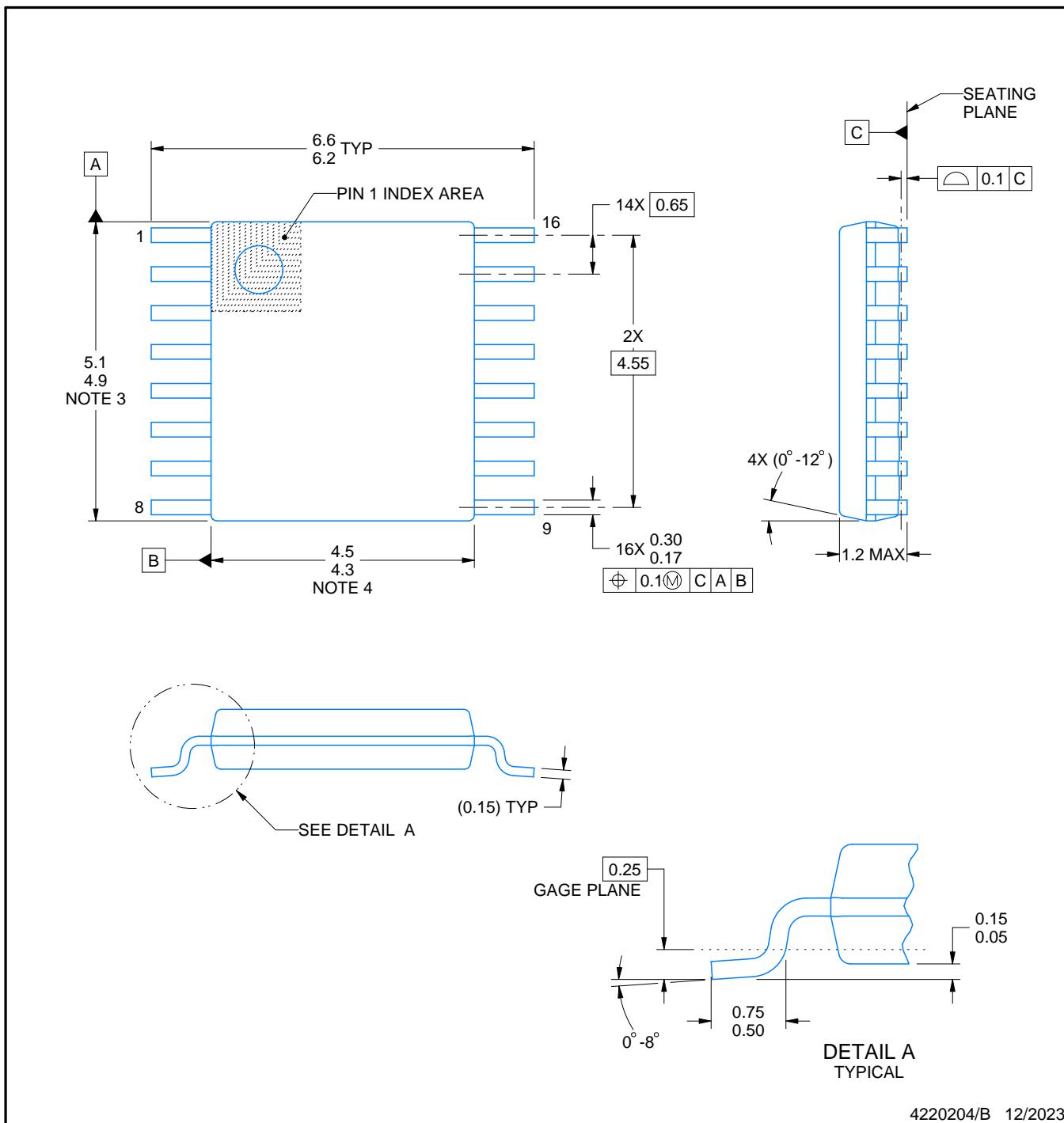
SEATING PLANE

PIN 1 INDEX AREA

6.6
6.2 TYP

14X 0.65

2X 4.55

5.1
4.9
NOTE 3

4.5
4.3
NOTE 4

16X 0.30
0.17

⊕ 0.1 Ⓜ C A B

0.1 C

4X (0°-12°)

1.2 MAX

SEE DETAIL A

(0.15) TYP

GAGE PLANE

0.25

0.15
0.05

0.75
0.50

0°-8°

DETAIL A
TYPICAL

4220204/B   12/2023

NOTES:
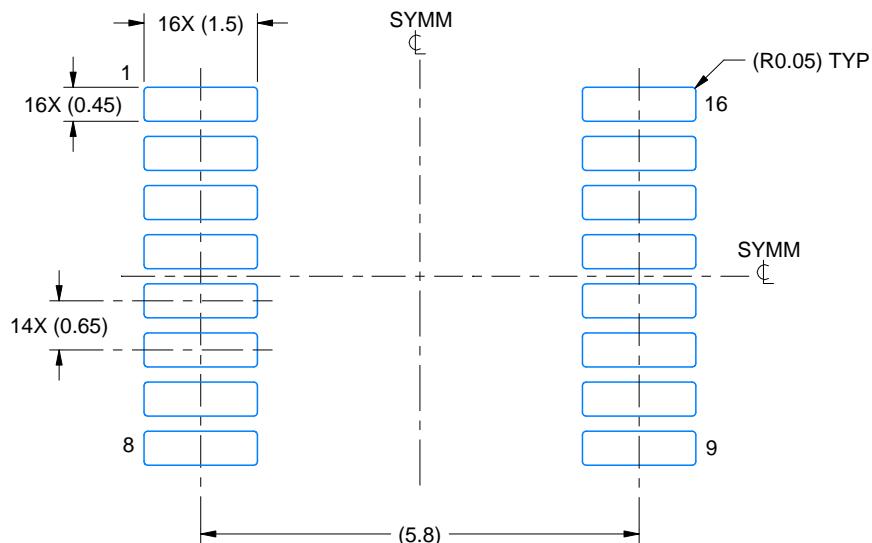
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

16X (1.5)

SYMM

1

16X (0.45)

(R0.05) TYP

16

SYMM

14X (0.65)

8

9

(5.8)
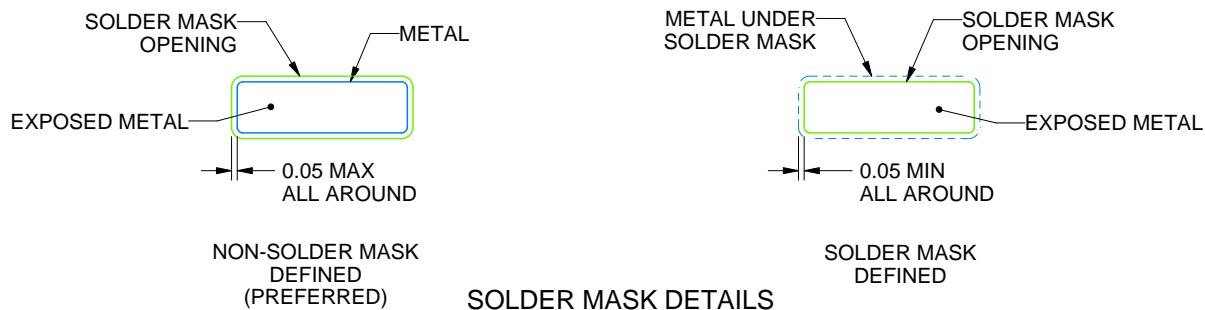
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK
OPENING

METAL

EXPOSED METAL

0.05 MAX
ALL AROUND

NON-SOLDER MASK
DEFINED
(PREFERRED)

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

EXPOSED METAL

0.05 MIN
ALL AROUND

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220204/B   12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
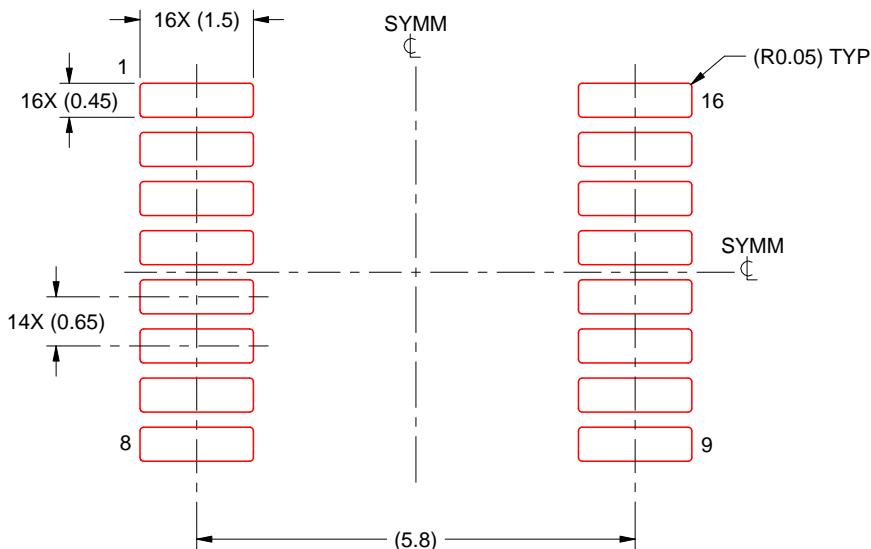
16X (1.5)

SYMM

1

16X (0.45)

(R0.05) TYP

16

SYMM

14X (0.65)

8

9

(5.8)

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B   12/2023
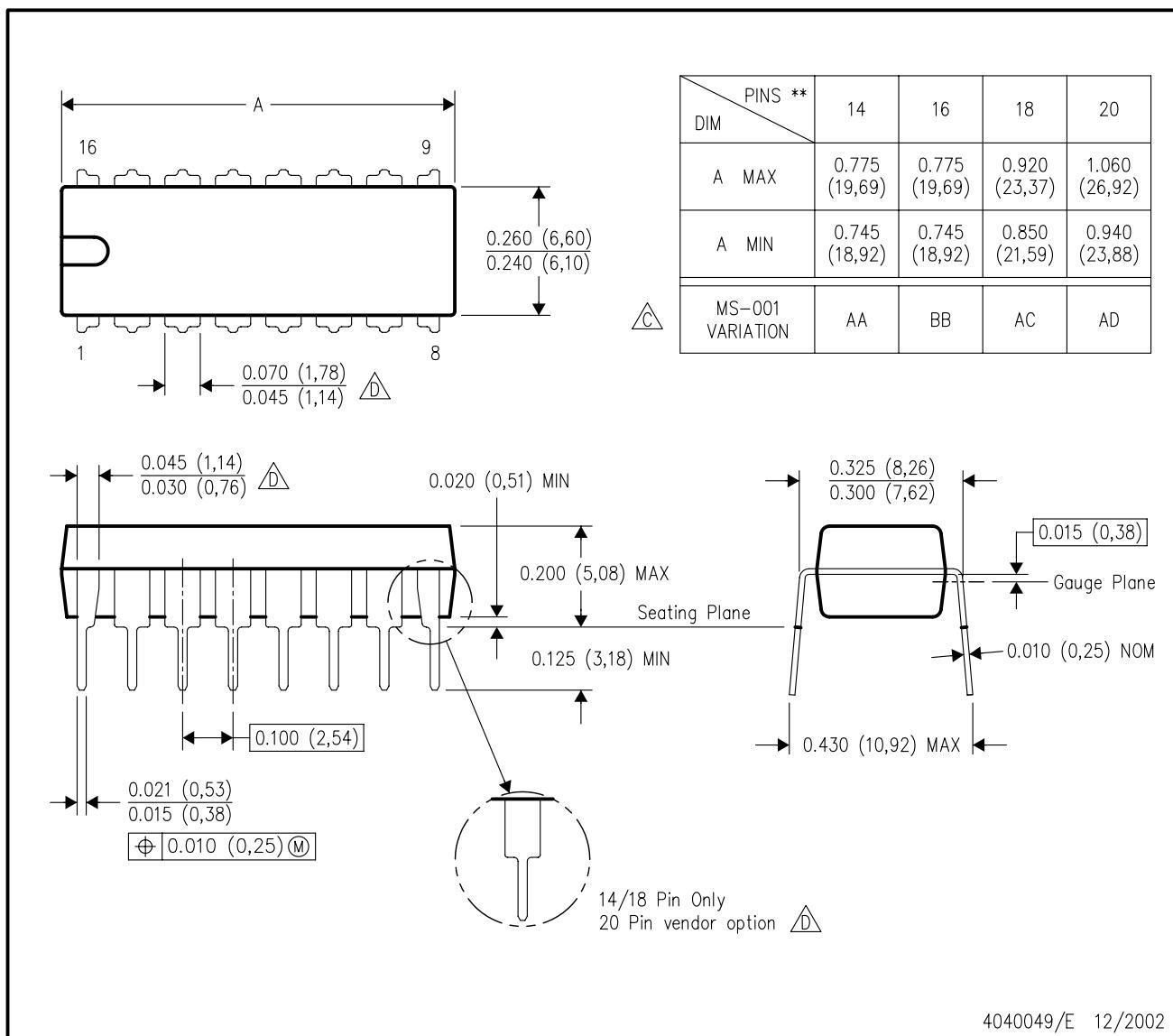
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
   design recommendations.
9. Board assembly site may have different recommendations for stencil design.

N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION	AA	BB	AC	AD

A

16   9

0.260 (6,60)
0.240 (6,10)

1   8

0.070 (1,78)
0.045 (1,14) △D

0.045 (1,14)
0.030 (0,76) △D

0.020 (0,51) MIN

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.200 (5,08) MAX

Seating Plane

0.010 (0,25) NOM

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

0.430 (10,92) MAX

14/18 Pin Only
20 Pin vendor option △D

4040049/E   12/2002

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
       △C   Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
       △D   The 20 pin end lead shoulder width is a vendor option, either half or full width.

8.2
7.4 TYP

A

PIN 1 ID
AREA

1

16

14X 1.27

10.4
10.0
NOTE 3

2X
8.89

8

9

B

5.4
5.2
NOTE 4

16X 0.51
0.35

⌖ 0.25Ⓜ C A B

C

SEATING PLANE

⌒ 0.1 C

2.00 MAX

SEE DETAIL A

0.15 TYP

0.25

GAGE PLANE

0.3
0.1

0°-10°

1.05
0.55

(1.25)

DETAIL A
TYPICAL

4220735/A   12/2021

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

16X (1.85)

SYMM
¢

SEE
DETAILS

1

16

16X (0.6)

SYMM
¢

14X (1.27)

8

9

(R0.05) TYP

(7)
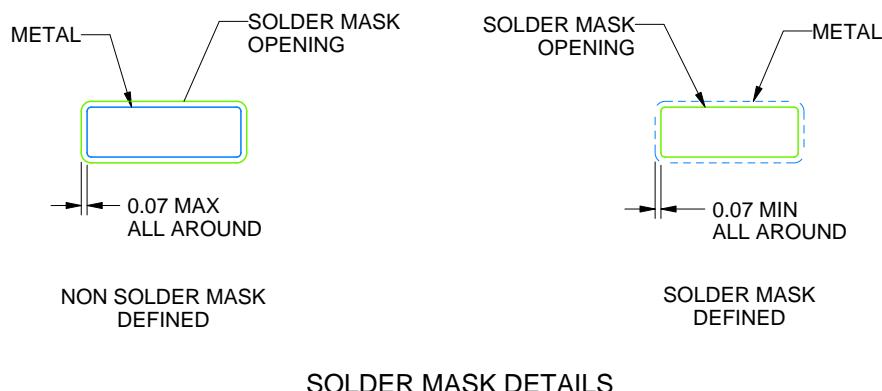
LAND PATTERN EXAMPLE
SCALE:7X

METAL

SOLDER MASK
OPENING

SOLDER MASK
OPENING

METAL

0.07 MAX
ALL AROUND

0.07 MIN
ALL AROUND

NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A   12/2021

NOTES: (continued)
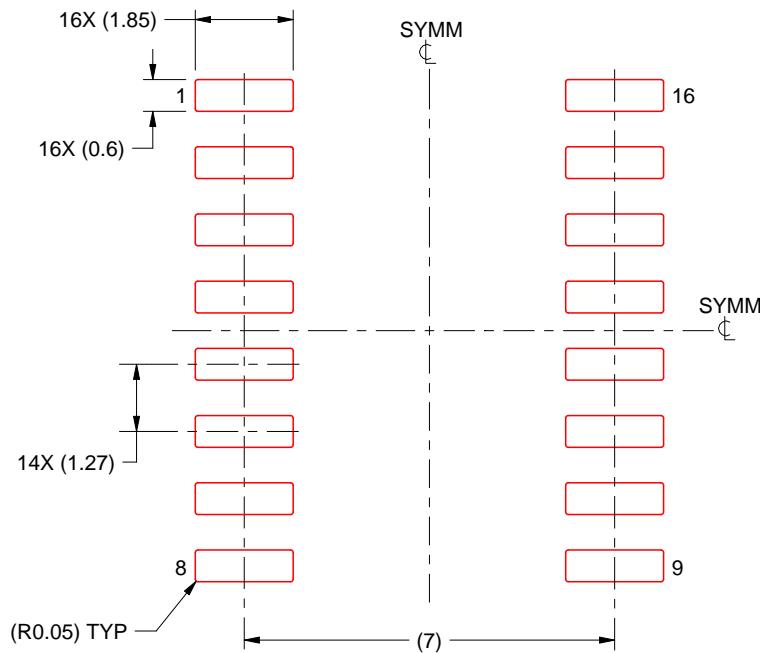
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

16X (1.85)

SYMM

1

16

16X (0.6)

SYMM

14X (1.27)

8

9

(R0.05) TYP

(7)

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A   12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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